

Method for mounting terminal on circuit board and circuit board

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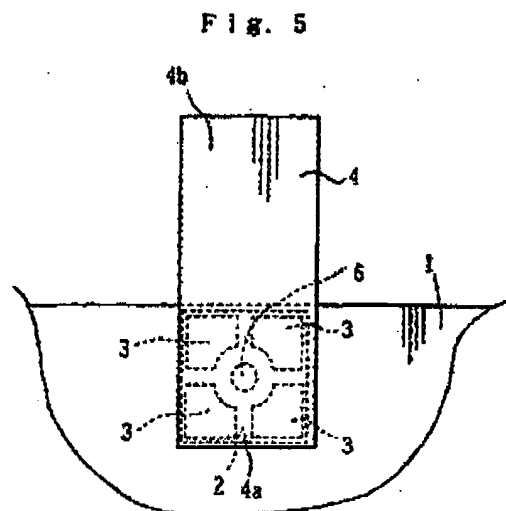
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There are provided a coating step for coating solder paste (3) onto the circuit board (1), a superimposing step for superimposing a connecting end (4a) of a terminal (4) also having a non-connecting end (4b) on the regions coated with solder paste (3), and a heating step for heating and melting the solder paste (3) in order to solder the connecting end (4a) onto the circuit board (1). A further step for coating adhesive material (6) onto the circuit board (1) is provided, and in the aforementioned superimposing step, the connecting end (4a) is brought into contact with the regions coated with the adhesive material (6). In the aforementioned heating step, the solder paste (3) is heated and caused to melt whilst the connecting end (4a) is in a



bonded state with respect to the
circuit board (1) by means of the
adhesive material (6).

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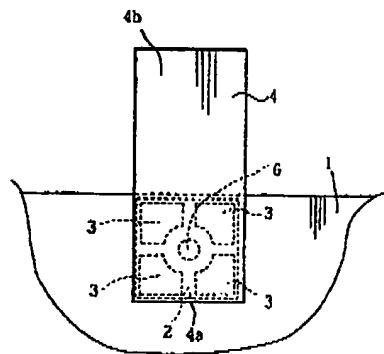
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权利要求书 2 页 说明书 13 页 附图 15 页

[54] 发明名称 电路板上接线端的安装方法以及电路板

[57] 摘要

一种电路板上接线端的安装方法具备有在电路板(1)上涂抹焊膏(3)的涂抹工序、把具有连接端(4a)和非连接端(4b)的接线端(4)的连接端(4a)与焊膏(3)涂抹区重叠的重叠工序和为把连接端(4a)焊在电路板(1)上加热熔融焊膏(3)的加热工序,此外还具有在电路板(1)上涂抹粘合剂(6)的工序,上述重叠工序是使连接端(4a)与粘合剂(6)的涂抹区接触,上述加热工序是在通过粘合剂(6)使连接端(4a)粘合在电路板(1)上的状态下加热熔融焊膏(3)。



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